

Socket Adapter Technology

High quality socket adapter solutions to reduce cost and maxmize your programming yield



Standard Socket Adapters

- ✓ Ideal for low to medium volume applications
- ✓ Supports the widest variety of device packages and thickness
- ✓ Proven socket adapter solutions

Medium Insertion Count (MIC) Socket Adapters

- ✓ Designed for medium to high volume applications
- ✓ Up to 50,000 insertions per socket
- ✓ Cost effective solution delivering high programming yields

High Insertion Count (HIC) Socket Adapters

- ✓ Highest quality components for high-volume programming applications
- ✓ Proprietary adapter design with up to 250,000 insertions per socket
- ✓ Delivers the industry's lowest cost per programmed device at ~US\$0.01





Standard Socket Adapter Features

- Typical life is 5,000~10,000 insertions per socket
- Supports BGA, CSP, SO, TSOP, QFN, USON, QFP, PLCC, DIP...
- FlashCORE III socket adapter capacity: up to 4 sockets per programmer
- LumenX socket adapter capacity: 1 socket per adapter and up to 8 adapters per programmer
- Status LEDS



FlashCORE Standard Adapter



LumenX Standard Adapter

Middle Insertion Count (MIC) Socket Adapter Features

- Typical life is 50,000 insertions per socket
- Supports BGA, CSP, SO, QFN, USON...
- FlashCORE III socket adapter capacity: up to 4 sockets per programmer
- LumenX socket adapter capacity: 1 socket per adapter and up to 8 adapters per programmer
- Status LEDS



FlashCORE MIC Adapter



LumenX MIC Adapter

High Insertion Count (HIC) Socket Adapter Features

- Typical life is 125,000~250,000 insertions per socket
- Typical yields are 99.8% and higher
- Supports BGA, CSP, WLCSP, SO, TSOP, QFN, USON, QFP ...
- FlashCORE III socket adapter capacity: up to 4 sockets per programmer
- LumenX socket adapter capacity: 1 socket per adapter and up to 8 adapters per programmer
- Status LEDS
- Removable sockets



FlashCORE HIC Adapter



LumenX HIC Adapter

Socket Type	Standard Burn In Socket		Medium Insertion Socket	High Insertion Socket	
Device Package	BGA,WLCSP	QFP, TSOP, QFN, MLF	BGA, QFP, TSOP, MLF, WLCSP	BGA,WLCSP	QFP, TSOP, QFN, MLF
Insertions Per Socket (Mechanical Life Cycle)	5,000	10,000	50,000	250,000	125,000
Cost Per Device(US\$)	0.04-0.08		~0.025	~0.01	
Programming Applications	Low to medium		Medium to high volume	High volume	
Typical Yield	97%		98.5%	99.8%	
Maintenance Need	High	Medium	Low	Very Low	
Maintenance Process	Compressed Air		Cleaning with ProGold Wipes and Nanotek Brush	Cleaning with ProGold Wipes and Nanotek Brush	
Note	1) The performance characteristic of any socket in programming depends on a variety of factors including (but not limited to) solder alloy composites, tolerances, temperature, physical environment (dust) and cleanliness, and contact exposure time. 2) The mentioned cycles are indication for mechanical cycles.				

^{*}Standard adapter insertion count may vary depending on socket type. Please contact Data I/O for additional information.

